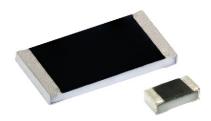


Lead (Pb)-Bearing Sulfur Resistant Thick Film Chip Resistors



LINKS TO ADDITIONAL RESOURCES



The lead (Pb)-bearing sulfur resistant, thick film chip resistors series is the perfect choice for most fields of harsh environment electronics operation, where lead (Pb)-bearing terminations are mandatory, and high reliability and stability are of major concern.

Typical applications include industrial and military applications which operate in harsh environment.

FEATURES

HALOGEN FREE

- Superior resistance against sulfur containing atmosphere, according to ASTM B809-95
- Stability at different environmental conditions ΔR/R ≤ 1 % (1000 h rated power at 70 °C)
- AEC-Q200 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Industrial
- Military

TECHNICAL SPECIFIC		T =	T =	T			T	1
DESCRIPTION	RCA0402	RCA0603	RCA0805	RCA1206	RCA1210	RCA1218	RCA2010	RCA2512
Imperial size	0402	0603	0805	1206	1210	1218	2010	2512
Metric size code	RR1005M	RR1608M	RR2012M	RR3216M	RR3225M	RR3246M	RR5025M	RR6332M
Resistance range		1 Ω to	10 MΩ; jump	er (0 Ω)		1 Ω to 2.2 M Ω ; jumper (0 Ω)		10 MΩ; er (0 Ω)
Resistance tolerance				±5 %; ±	1 %; ± 0.5 %	Ď		
Temperature coefficient			± 20	0 ppm/K; ± 10	00 ppm/K; ±	50 ppm/K		
Rated dissipation, P ₇₀ ⁽¹⁾	0.063 W	0.10 W	0.125 W	0.25 W	0.5 W	1.0 W	0.75 W	1.0 W
Operating voltage, <i>U</i> _{max.} AC _{RMS} /DC	50 V	75 V	150 V	200 V	200 V	200 V	400 V	500 V
Permissible film temperature, $v_{\rm F\ max.}^{(1)}$				1	55 °C			
Operating temperature range				-55 °C	to +155 °C			
Maximum resistance change at P_{70} for resistance range, $ \Delta R/R $ after:								
1000 h	≤ 1.0 %							
Permissible voltage against ambient (insulation):								
1 min, <i>U</i> _{ins}	75 V	100 V	200 V	300 V	300 V	300 V	300 V	300 V
Failure rate: FIT _{observed}		≤ 0.1 x 10 ⁻⁹ /h						

Note

APPLICATION INFORMATION

When the resistor dissipates power, a temperature rise above the ambient temperature occurs, dependent on the thermal resistance of the assembled resistor together with the printed circuit board. The rated dissipation applies only if the permitted film temperature is not exceeded.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.

⁽¹⁾ Please refer to APPLICATION INFORMATION below



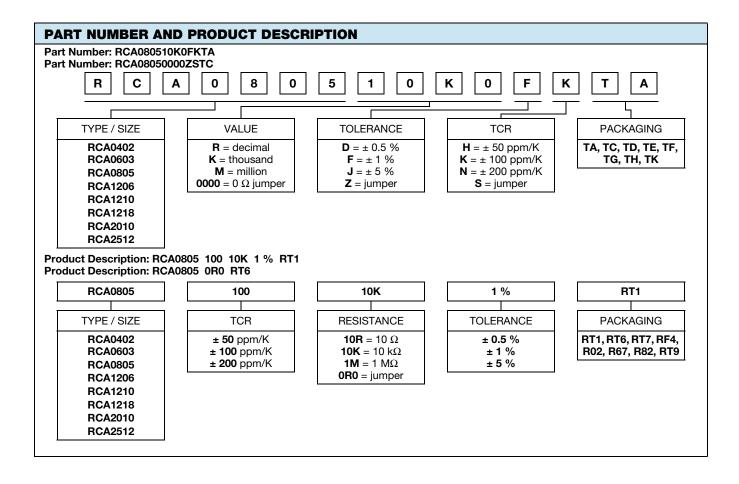
TEMPERATU	RE COEFFICIENT AND	RESISTANCE RANG	E	
TYPE / SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES
	± 200 ppm/K	± 5 %	1.0 Ω to 10 M Ω	E24
	± 200 ppm/K	± 1 %	1.0 Ω to 9.76 Ω	E24; E96
	± 100 ppm/K	± 1 %	10 Ω to 10 MΩ	E24; E96
RCA0402	± 100 ppm/K	± 0.5 %	10 Ω to 1.0 M Ω	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 1.0 M Ω	E24; E96
	Jumper, I _{max.} = 1.5 A	≤ 20 mΩ	0 Ω	-
	± 200 ppm/K	± 5 %	1.0 Ω to 10 M Ω	E24
	± 100 ppm/K	± 1 %	1.0 Ω to 10 M Ω	E24; E96
RCA0603	± 100 ppm/K	± 0.5 %	10 Ω to 10 MΩ	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 10 M Ω	E24; E96
	Jumper, I _{max.} = 2.0 A	≤ 20 mΩ	0 Ω	-
	± 200 ppm/K	± 5 %	1.0 Ω to 10 M Ω	E24
	± 100 ppm/K	± 1 %	1.0 Ω to 10 M Ω	E24; E96
RCA0805	± 100 ppm/K	± 0.5 %	10 Ω to 10 MΩ	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 10 MΩ	E24; E96
	Jumper, I _{max.} = 2.5 A	≤ 20 mΩ	0 Ω	-
RCA1206	± 200 ppm/K	± 5 %	1.0 Ω to 10 MΩ	E24
	± 100 ppm/K	± 1 %	1.0 Ω to 10 MΩ	E24; E96
	± 100 ppm/K	± 0.5 %	10 Ω to 10 MΩ	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 10 MΩ	E24; E96
	Jumper, I _{max.} = 3.5 A	≤ 20 mΩ	0 Ω	-
	± 200 ppm/K	± 5 %	1.0 Ω to 10 MΩ	E24
	± 100 ppm/K	± 1 %	1.0 Ω to 10 MΩ	E24; E96
RCA1210	± 100 ppm/K	± 0.5 %	10 Ω to 1.0 MΩ	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 1.0 MΩ	E24; E96
	Jumper, I _{max.} = 5.0 A	≤ 20 mΩ	0 Ω	-
	± 200 ppm/K	± 5 %	1.0 Ω to 2.2 M Ω	E24
	± 100 ppm/K	± 1 %	1.0 Ω to 2.2 MΩ	E24; E96
RCA1218	± 100 ppm/K	± 0.5 %	100 Ω to 2.2 MΩ	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 2.2 MΩ	E24; E96
	Jumper, I _{max.} = 7.0 A	≤ 20 mΩ	0 Ω	-
	± 200 ppm/K	± 5 %	1.0 Ω to 10 MΩ	E24
	± 100 ppm/K	± 1 %	1.0 Ω to 10 MΩ	E24; E96
RCA2010	± 100 ppm/K	± 0.5 %	10 Ω to 10 MΩ	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 10 MΩ	E24; E96
	Jumper, I _{max.} = 6.0 A	≤ 20 mΩ	0 Ω	- -
	± 200 ppm/K	± 5 %	1.0 Ω to 10 MΩ	E24
	± 100 ppm/K	± 1 %	1.0 Ω to 10 MΩ	E24; E96
RCA2512	± 100 ppm/K	± 0.5 %	10 Ω to 10 MΩ	E24; E96
	± 50 ppm/K	± 0.5 %; ± 1 %	100 Ω to 10 MΩ	E24; E96
	Jumper, I _{max.} = 7.0 A	≤ 20 mΩ	0 Ω	

Note

- The temperature coefficient of resistance (TCR) is not specified for 0 Ω jumpers



PACKAGING	PACKAGING									
TYPE / SIZE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	PACKAGING DIMENSIONS				
RCA0402	TD = RT7	10 000		8 mm	2 mm	Ø 180 mm / 7"				
NOAU4U2	TE = RF4	50 000		0 111111	2 111111	Ø 330 mm / 13"				
RCA0603	TA = RT1	5000		8 mm	4 mm	Ø 180 mm / 7"				
HOA0003	TC = RT6	20 000			4 111111	Ø 330 mm / 13"				
RCA0805	TA = RT1	5000	Paper tape according to	8 mm	4 mm	Ø 180 mm / 7"				
NOAUOUS	TC = RT6	20 000	IEC 60286-3, type 1a			Ø 330 mm / 13"				
RCA1206	TA = RT1	5000		8 mm	4 mm	Ø 180 mm / 7"				
NCA1200	TC = RT6	20 000				Ø 330 mm / 13"				
RCA1210	TA = RT1	5000		0	4 mm	Ø 180 mm / 7"				
RCA1210	TC = RT6	20 000		8 mm	4 111111	Ø 330 mm / 13"				
RCA1218	TK = RT9	4000		12 mm	4 mm	Ø 180 mm / 7"				
RCA2010	TF = R02	4000	Blister tape according to	12 mm	4 mm	Ø 180 mm / 7"				
RCA2512	TG = R67	2000	IEC 60286-3, type 2a	12 mm	8 mm	Ø 190 mm / 7"				
	TH = R82	4000		12 (1)[1]	4 mm	Ø 180 mm / 7"				





DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A cermet film layer and a glass-over are deposited on a high grade (Al_2O_3) ceramic substrate with its prepared inner contacts. A special laser is used to achieve the target value by smoothly fine trimming the resistive layer without damaging the ceramics. A special process is used to ensure resistor long term operation in harsh environment (sulfur atmosphere). The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a SnPb layer on nickel plating.

The result of the determined production is verified by an extensive testing procedure on 100 % of the individual chip resistors. Only accepted products are laid directly into the tape in accordance with **IEC 60286-3 Type 1a and Type 2a** (1).

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering wave, reflow or vapor phase as shown in **IEC 61760-1** ⁽¹⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors with SnPb plating provides compatibility with lead (Pb)-free and lead (Pb)-containing soldering processes. Solderability is specified for 2 years after production or requalification. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

MATERIALS

Vishay acknowledges the following systems for the regulation of hazardous substances:

- IEC 62474, Material Declaration for Products of and for the Electrotechnical Industry, with the list of declarable substances given therein (2)
- \bullet The Global Automotive Declarable Substance List (GADSL) $^{(3)}$
- The REACH regulation (1907/2006/EC) and the related list of substances with very high concern (SVHC) (4) for its supply chain

Except for the intentionally added lead (Pb) in the termination finish, the products do not contain any of the banned substances as per IEC 62474, GADSL, or the SVHC list, see www.vishav.com/how/leadfree.

Vishay pursues the elimination of conflict minerals from its supply chain, see the Conflict Minerals Policy at www.vishay.com/doc?49037.

APPROVALS

The resistors are qualified according to AEC-Q200. Where applicable, the resistors are tested in accordance with **EN 140401-802** which refers to **EN 60115-1**, **EN 60115-8** and the variety of environmental test procedures of the **IEC 60068** ⁽¹⁾ series.

RELATED PRODUCTS

For more information about RoHS-compliant products with sulfur resistance, please refer to datasheet:

RCA e3 Sulfur Resistant Thick Film Chip Resistors

www.vishay.com/doc?20037

D/CRCW series is not designed for sulfur-containing environment applications.

For ordering D/CRCW lead (Pb)-bearing products, please refer to latest edition of datasheet:

www.vishay.com/doc?20008

For products with sulfur resistance, superior surge and pulse performance, please refer to datasheet:

RCA-IF e3, Pulse Proof Thick Film Chip Resistors www.vishay.com/doc?20059

For products with sulfur resistance and high power rating, please refer to datasheet:

RCA-HP e3, Pulse Proof High Power Thick Film Chip Resistors

www.vishay.com/doc?20065

For more information about long termination, RoHS-compliant products with sulfur resistance, please refer to datasheet:

RCA-LS e3 Sulfur Resistant Long Side Termination Thick Film Chip Resistors

www.vishay.com/doc?20060

Notes

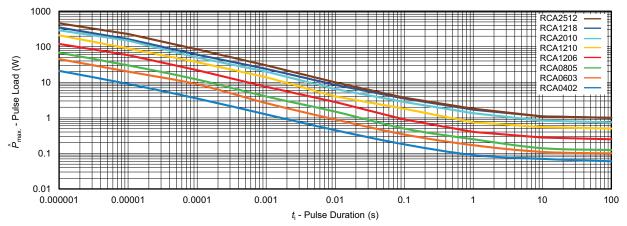
- (1) The quoted IEC standards are also released as EN standards with the same number and identical contents
- (2) The IEC 62474 list of declarable substances is maintained in a dedicated database, which is available at http://std.iec.ch/iec62474
- (3) The Global Automotive Declarable Substance List (GADSL) is maintained by the American Chemistry Council and available at www.gadsl.org
- (4) The SVHC list is maintained by the European Chemical Agency (ECHA) and available at http://echa.europa.eu/candidate-list-table



FUNCTIONAL PERFORMANCE

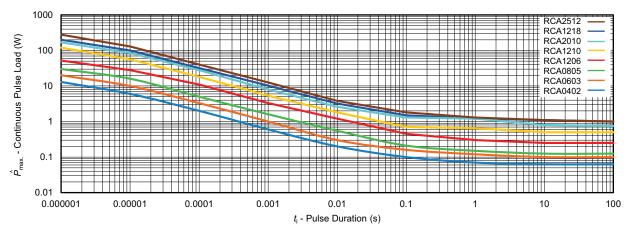
PERFORMANCE IN SULFUR-CONTAINING AMBIANCE							
TEST NAME	HUMID SULFUR VAPOR TEST	HUMID SULFUR VAPOR TEST (Accelerated)					
Reference specification	ASTM B809-95	ASTM B809-95 accelerated conditions					
Test conditions (temperature, humidity)	60 °C ± 2 °C 85 % ± 4 % RH	90 °C ± 2 °C 74 % ± 7 % RH					
Aggressive agent	Sulfur (saturated vapor)	Sulfur (saturated vapor)					
Failure criteria in VI under magnification	No silver sulfide growth at the interface between termination and protective overcoat. No signs of mechanical damage.	No silver sulfide growth at the interface between termination and protective overcoat. No signs of mechanical damage.					
Failure criteria in electrical test	≤ (± 1 % R + 0.05 Ω)	≤ (± 1 % R + 0.05 Ω)					
Time before failure	8000 h	1000 h					

Single Pulse



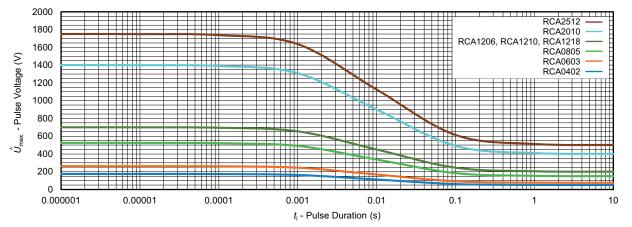
Maximum pulse load, single pulse; applicable if $\overline{P} \to 0$ and n < 1000 and $\hat{U} = \hat{U}_{\text{max}}$; for permissible resistance change equivalent to 8000 h operation

Continuous Pulse



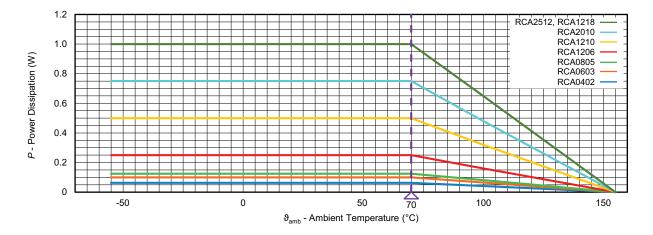
Maximum pulse load, continuous pulses; applicable if $\overline{P} \le P$ (ϑ_{amb}) and $\hat{U} = \hat{U}_{max}$; for permissible resistance change equivalent to 8000 h operation

Pulse Voltage



Maximum pulse voltage, single and continuous pulses; applicable if $\hat{P}=\hat{P}_{\text{max}}$; for permissible resistance change equivalent to 8000 h operation

Derating





TESTS AND REQUIREMENTS

All executed tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 60115-8, sectional specification

EN 140401-802, detail specification

IEC 60068-2-xx, test methods

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-802. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

Temperature: 15 °C to 35 °C Relative humidity: 25 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

A climatic category LCT / UCT / 56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on boards in accordance with EN 60115-8, 2.4.2 unless otherwise specified.

EN 60115-1	IEC 60068-2 ⁽¹⁾	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)		
CLAUSE	TEST METHOD			SIZE 0402	SIZE 0603 TO 2512	
			Stability for product types:	STABILITY CLAS	SS 2 OR BETTER	
			RCA	1 Ω to 10 MΩ		
6.1	-	Measurements of resistance and tolerance	-	± 5 %; ± 1 %; ± 0.5 %		
6.2	-	Temperature coefficient of resistance	(20 / -55 / 20) °C and (20 / 155 / 20) °C	± 200 ppm/K; ± 100	ppm/K; ± 50 ppm/K	
7.1	-	Endurance at rated temperature 70 °C	$U = \sqrt{P_{70} \times R} \le U_{\text{max.}};$ 1.5 h on; 0.5 h off			
		temperature 70 C	70 °C; 1000 h	$\pm (1 \% R + 0.05 \Omega)$	± (0.5 % R + 0.05 Ω	
7.3	-	Endurance at maximum temperature	155 °C, 1000 h	± (0.5 % F	? + 0.05 Ω)	
10.4	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; (93 ± 3) % RH; 56 days	± (1 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)	
10.5	67 (Cy)	Damp heat, steady state, accelerated	$U = \sqrt{0.1 \times P_{85} \times R}; U \le 100 \text{ V};$ $U = \sqrt{0.1 \times P_{85} \times R}; U \le 100 \text{ V};$ 1000 h	± (1 % R + 0.05 Ω)		
10.3	-	Climatic sequence:	-			
10.3.4.2	2 (Ba)	Dry heat	125 °C; 16 h			
10.3.4.3	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 % RH; 24 h; 1 cycle			
10.3.4.4	1 (Ab)	Cold	-55 °C; 2 h	± (1 % R	+ 0.05 Ω)	
10.3.4.5	13 (M)	Low air pressure	1 kPa; 1 h; (25 ± 10) °C 55 °C; > 90 % RH	_ (, ,,,,		
10.3.4.6	30 (Db)	Damp heat, cyclic	24 h; 5 cycles			
10.3.4.7	-	DC load	$U = \sqrt{P_{70} \times R} \le U_{\text{max.}}$; 1 min			
-	1 (Aa)	Cold	-55 °C; 2 h	± (0.25 %	R + 0.05 Ω)	
10.1	14 (Na)	Rapid change of temperature	30 min at -55 °C and 30 min at 125 °C; 1000 cycles	± (1 % R + 0.05 Ω)		
8.1	-	Short-term overload	$U = 2.5 \text{ x} \sqrt{P_{70} \text{ x } R} \le 2 \text{ x } U_{\text{max.;}}$ whichever is the less severe; 5 s	± (2 % R	+ 0.05 Ω)	



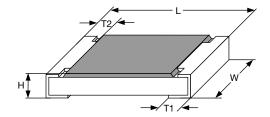
EN 60115-1	IEC 60068-2 ⁽¹⁾	TEST	PROCEDURE		EMENTS CHANGE (△ <i>R</i>)	
CLAUSE	TEST METHOD			SIZE 0402	SIZE 0603 TO 2512	
			Stability for product types:	STABILITY CLASS 2 OR BETTER		
			RCA	1 Ω to 10 MΩ		
8.2	-	Single pulse high voltage overload	Severity no. 4: $U = 10 \times \sqrt{P_{70} \times R}$ or $U \le 2 \times U_{\text{max.}}$; whichever is the less severe 10 pulses 10 µs / 700 µs	± (1 % <i>R</i>	+ 0.05 Ω)	
8.4	-	Periodic electric overload	$U = \sqrt{15 \times P_{70} \times R} \le 2 \times U_{\text{max.}}$ whichever is the less severe; 0.1 s on; 2.5 s off; 1000 cycles	± (1 % R	+ 0.05 Ω)	
8.5	-	Electrostatic discharge (human body model)	IEC 61340-3-1 ⁽¹⁾ ; 3 pos. + 3 neg. discharges; ESD voltage according to the size	± (1 % R	+ 0.05 Ω)	
9.11	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude \leq 1.5 mm or \leq 200 m/s ² ; 7.5 h	± (0.25 %	R + 0.05 Ω)	
11.1	58 (Td)	Solderability	Solder bath method; Sn60Pb40 non-activated flux; (235 ± 5) °C; (2 ± 0.2) s Solder bath method;		≥ 95 % covered) e damage	
			Sn96.5Ag3Cu0.5 or Sn99.3Cu0.7 non-activated flux; (245 ± 5) °C or (250 ± 5) °C (3 ± 0.3) s			
11.2	58 (Td)	Resistance to soldering heat	Solder bath method (260 \pm 5) °C; (10 \pm 1) s	± (0.25 %	R + 0.05 Ω)	
11.3	45 (XA)	Component solvent resistance	Isopropyl alcohol; +50 °C; method 2	No visible damage		
9.7	21 (Ue ₃)	Shear (adhesion)	RCA0402 and RCA0603: 9 N RCA0805 to RCA2512: 17.7 N	No visible damage		
9.8	21 (Ue ₁)	Substrate bending	Depth 2 mm; 3 times	\pm (0.25 % R + 0.05 Ω) no visible damage, no open circuit in bent position		
12.2	-	Voltage proof	$U = 1.4 \times U_{ins}$; 60 s	No flashover	or breakdown	
12.4	-	Flammability, needle flame test	IEC 60695-11-5 ⁽¹⁾ ; 10 s	No burnin	g after 30 s	

Note

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents

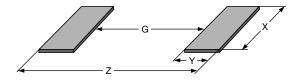


DIMENSIONS



DIMENSIONS AND MASS									
TYPE / SIZE	L (mm)	W (mm)	H (mm)	T1 (mm)	T2 (mm)	MASS (mg)			
RCA0402	1.0 ± 0.05	0.5 ± 0.05	0.35 ± 0.05	0.25 ± 0.10	0.2 ± 0.10	0.65			
RCA0603	1.55 + 0.10 / - 0.05	0.85 ± 0.1	0.45 ± 0.05	0.3 ± 0.20	0.3 ± 0.20	2			
RCA0805	2.0 + 0.20 / - 0.10	1.25 ± 0.15	0.5 ± 0.10	0.3 + 0.20 / - 0.10	0.3 ± 0.20	5.5			
RCA1206	3.2 + 0.10 / - 0.20	1.6 ± 0.15	0.55 + 0.05	0.45 ± 0.20	0.4 ± 0.20	10			
RCA1210	3.2 ± 0.20	2.5 ± 0.20	0.55 ± 0.05	0.45 ± 0.20	0.4 ± 0.20	16			
RCA1218	3.2 + 0.10 / - 0.20	4.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.20	0.4 ± 0.20	29.5			
RCA2010	5.0 ± 0.15	2.5 ± 0.15	0.6 ± 0.10	0.6 ± 0.20	0.6 ± 0.20	25.5			
RCA2512	6.3 ± 0.20	3.15 ± 0.15	0.6 ± 0.10	0.6 ± 0.20	0.6 ± 0.20	40.5			

SOLDER PAD DIMENSIONS



RECOMMENDED SOLDER PAD DIMENSIONS								
		WAVE SO	LDERING		REFLOW SOLDERING			
TYPE / SIZE	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)
RCA0402	-	-	-	-	0.45	0.60	0.60	1.65
RCA0603	0.65	1.10	1.25	2.85	0.75	0.75	1.00	2.25
RCA0805	0.90	1.30	1.60	3.50	1.00	0.95	1.45	2.90
RCA1206	1.40	1.40	1.95	4.20	1.50	1.05	1.80	3.60
RCA1210	1.80	1.45	2.95	4.70	1.70	1.10	2.80	3.90
RCA1218	1.80	1.30	5.10	4.40	1.90	1.10	4.90	4.10
RCA2010	3.40	1.65	2.85	6.70	3.50	1.45	2.80	6.40
RCA2512	4.60	1.60	3.65	7.80	4.75	1.45	3.50	7.65

Notes

- The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g in standards IEC 61188-5-x (1) or in publication IPC-7351.
 - Still, the given solder pad dimensions will be found adequate for most general applications
- (1) The quoted IEC standards are also released as EN standards with the same number and identical contents



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Vishay

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